

PowerSpector

GTAz



In-Line 3D Automatic Optical Inspection systems

- √ Revolutionary 3D imaging technology
- √ High Speed 90Fps USB 3 Vision Cameras
- √ 2X FOV over previous Generation
- √ Multi-color 4 angle lighting with Line Source Coaxial Lighting and Meniscus Profiler
- √ Inspects:
 - Components: SMT & THT (missing, type, polarity, offset, text, colors, etc.)
 - Component Height and Coplanarity
 - Solder Paste and CIP (Components in Paste; pre-reflow)
 - Soldering: Post Reflow, Post Wave, Selective, Manual
- √ Flexible classification and reporting scenarios.....
- √ Line Sourced DOAL(Direct On Axis Lighting) coaxial lighting system with high resolution Telecentric Optics.....
- √ Low Noise Large CCD High Speed 24 bit Color Camera
- √ Synthetic Imaging and Spectral Analysis.....
- √ Triple use of side camera's
- √ Prototype mode for 1st off inspection.....
- √ In height adjustable optical head

True 3D imaging, Side cameras integrated in 3D processing.

*The latest generation of high speed, high quality cameras
No capture card requirements.*

Up to 50% reduction of cycle time.

reliable solder joint meniscus and pad surface analysis (to find meniscus and paste printing defects)

use inspection in all stages of the production process

integrate AOI efficiently in your existing operations and factory lay-out

inspect solder joints without shadow effects from tall components nearby and accurate inspection model building

find defects easier including printing defects on Gold or Cu plated PCB's

powerful algorithms to achieve an optimal balance between defect detection and false reject levels in shortest time

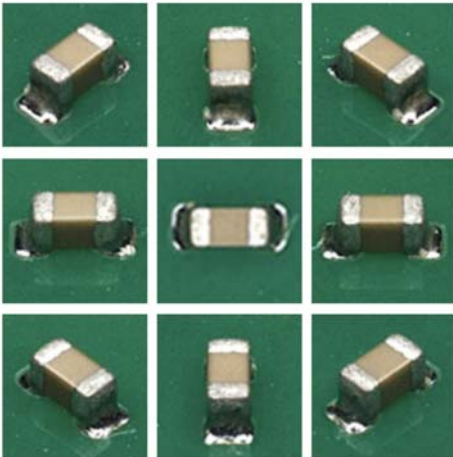
Use for automatic inspection, classification and repair

program in minutes to verify your production line is set-up correctly before starting full production

Compensate for PCB warp and adapt to tall component and sandwich assemblies

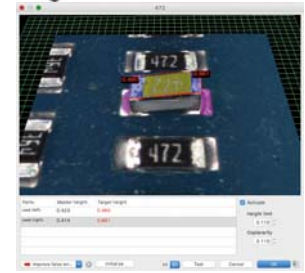
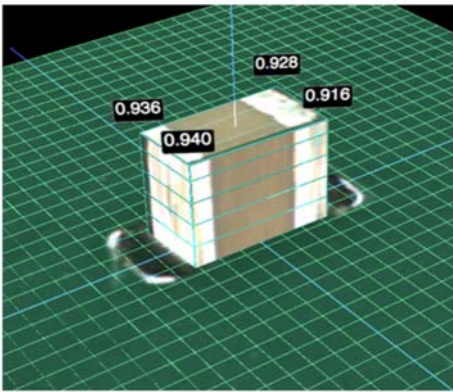
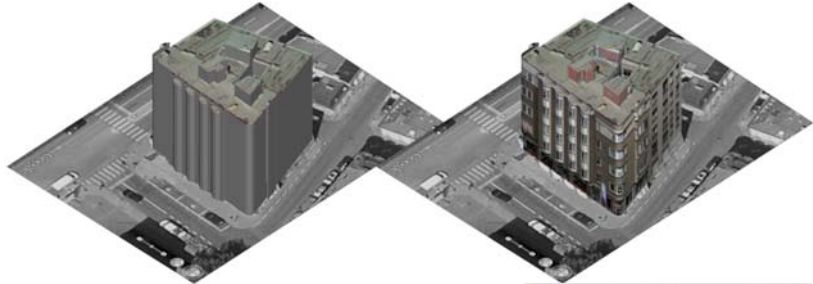
because inspection matters

Hardware and Software Features



Revolutionary 3D imaging

True Stereoscopic imaging using 9 cameras. Full colour 3D allows the ability to actually see the side of components rather than extruded 2D images. Using the addition of a 4th LED white light

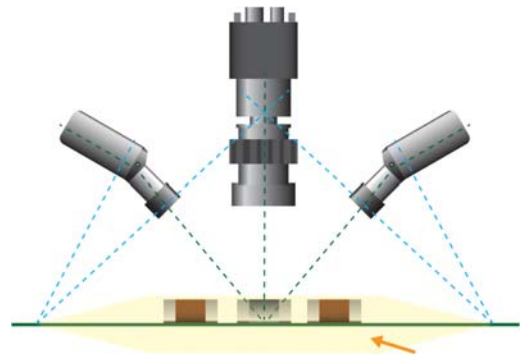


The perfect combination of 3D and 2D inspection

Height, tilt and coplanarity measurement. Pin Height measurement Component Presence Absence, Polarity, Value, Angle, Offset, Colour, Extra part detection, Solder ball detection, Solder profile analysis and short detection. The thickness of chip capacitors in combination with colour makes a more reliable inspection when checking chip capacitors value.

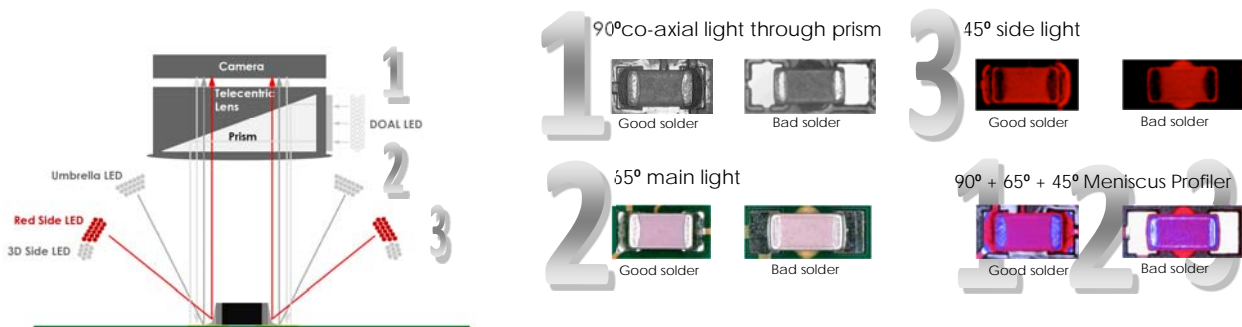
Unique 3D Stereoscopic Vision

Utilizing the full 9 cameras of the MEK camera head. The image differential are merged and a vectorised map of the component is created. Then analyzed based on the programmers applied tolerances. The vectorised map of the components removes the minor imperfection of the component surface giving more accurate measurement of height and surface angle of the component with reduced chance of false readings.



Omnidirectional multi angle, multi color LED lighting

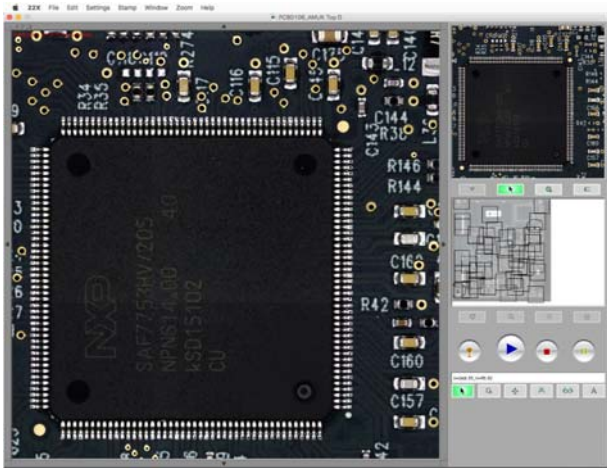
Optimal light no matter component direction — 3D color profile of solder meniscus — Reliable defect decision by the software — Decide Good Solder, No Solder, Lack of Solder and Too much solder for SMT and THT solder joints



8x Angular Side Sensors (Only available for FDA and FDAz models)

Simultaneously operating, multiplexed side view sensors with CameraLink interface — 45/45 arrangement — Triple use: Active automatic inspection, classification and repair — clear 9 angles defect review — high magnification 50x (10µm/pixel) — Full Color — Auto highlight — Large sensor pixels — 9 view images also in backup database

Hardware and Software Features — Continued



Double size FOV (Field of view)

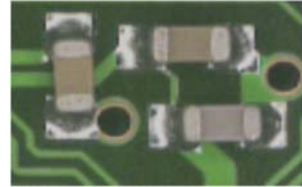
Up to 2x faster inspection over previous generations of machines. Square FOV combined with circular lighting allows for program rotation without time consuming debugging.

Large pixel image capturing sensor

18.8µm² pixel size — less noise — smooth and detailed image— great dynamic range



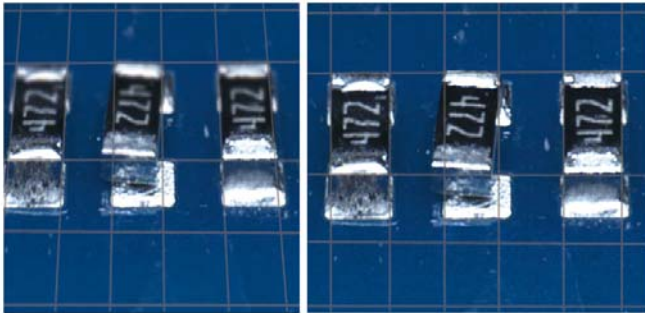
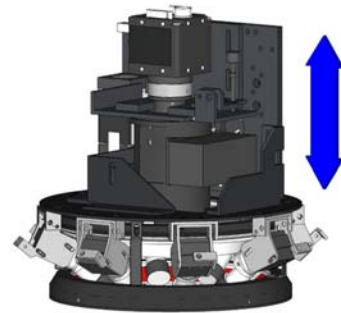
High dynamics sensor



Conventional sensor

In Height Adjustable Optical Head

In Z-Axis moving Top Camera, Light and Side View cameras — Adaption to any PCB Thickness — PCB Warp Compensation — Inspection of PCB's with very tall components — Reliable text and/or polarity inspection on tall components
Inspection of "Sandwich" assemblies without need of jigs and multiple inspections

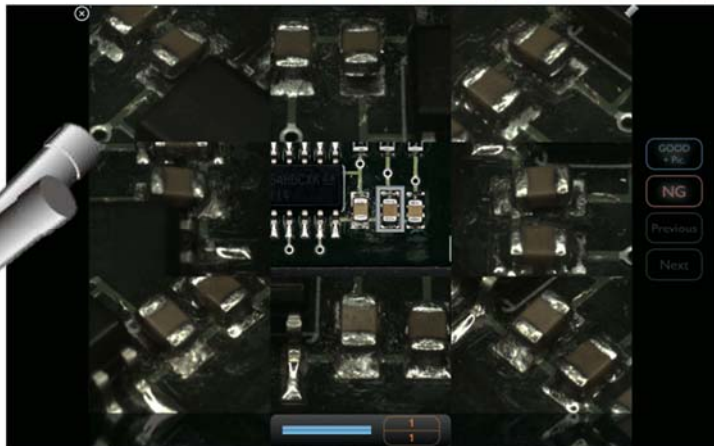
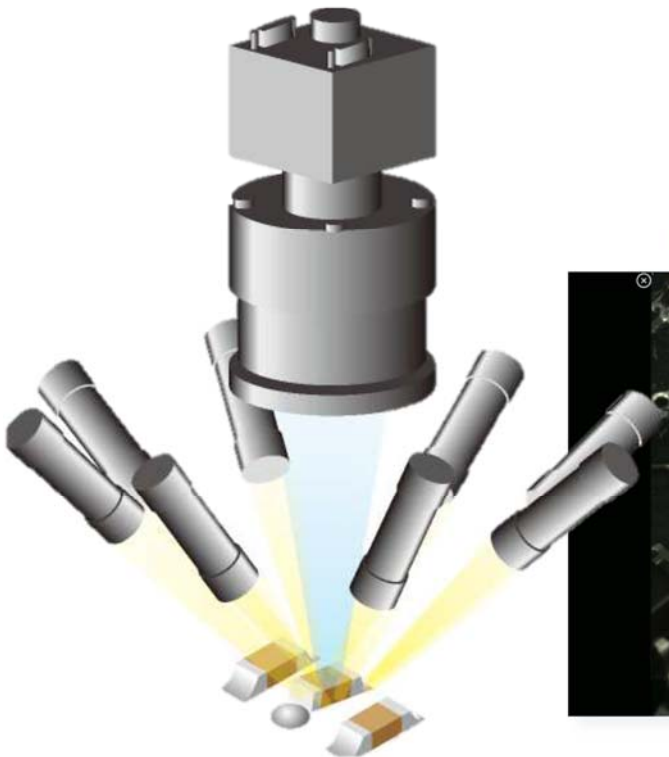
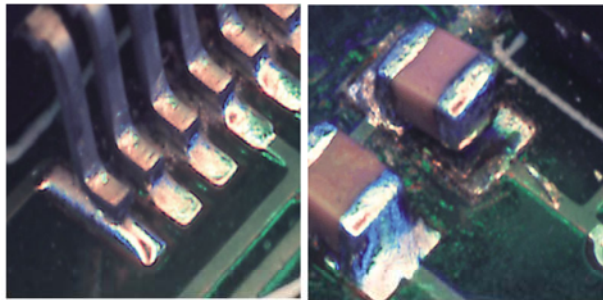


Without Shift&Tilt

Shift&Tilt

Shift & Tilt Side View lenses

Distortion free side images across whole FoV. Every point on the PCB within the FoV has same distance to the capturing sensor despite the angle of the optics



Inline

PowerSpector

GTAz

350L, 650L, 800L

because inspection matters

In-Line Series Specifications	PowerSpector GTAz 350L	PowerSpector GTAz 650L	PowerSpector GTAz 800L
Maximum PCB Size	350x250mm (13.8"x9.8")	650x550mm (25.6"x21.6")	800x550mm (31.5"x21.6")
<i>Characteristics</i>			
Product type	Automatic Optical Inspector		
In-line/Off-line	In-Line		
Camera movement	X + Y Direction		
PCB movement	Stationary during inspection		
Parts inspection	Presence, Polarity, Offset, Correctness, Soldering, Height		
Printing/paste inspection	Offset, Smearing, Bridges, Uniformity		
Image Processing	Synthetic Imaging, Spectral Analysis, Greyscale limits		
Image Parameters	Brightness, Hue, Saturation via Filters		
Camera type	Digital <i>color</i> Thunderbolt interface 90 Fps		
Camera Field Of View/Resolution	38.5x38.5mm/18.75µm or 19.5x19.5mm/10µm		
Lens	Telecentric lens with built in prism for DOAL Lighting		
Lighting system	Omnidirectional T Quad LED rings: Side White, Side Red, Main, Line Sourced DOAL (Diffused On Axis Lighting (Coaxial))		
<i>Specifications</i>			
Minimum inspection component size	01005" (0.4x0.2mm)(10µm resolution)		
Positioning accuracy	Pixel related Feedback Loop		
Component clearance (top)	30mm (1.2")		
Side Cameras	8x Digital <i>color</i> USB 3.0 Vision in 45/45 orientation		
Z-Axis movement range	30mm (1.2")		
Component clearance (bottom)	35mm (1.38") or 55mm (2.17") without PCB support lift option		
Maximum PCB Size	350x250mm (13.8" x 9.8")	650x550mm (25.6" x 21.6")	800x550mm (31.5"x21.6")
Movement speed	720mm/s		
Inspection capacity typical	2750ppm		
Electrical requirements	100-240 VAC / 330W		
<i>Conveyor</i>			
Conveyor belt speed	10-500mm/s (0.4-19.7"/s)		
Conveyor configuration	Left>Right, Front rail fixed, Height 830-950mm		
PCB Clamping	Top Justified, Ruler Blade, Top & Edge Clamping, Sensor Stopper		
Minimum board size	50x50mm (2.0" x 2.0")		
Board thickness	0.6-2mm (option 0.6-4mm) (24mils - 79mils)		
PCB warpage compensation	Automatic PCB support Lift with magnetic pins (option)		
<i>Interfacing</i>			
Control PC type	Apple Mac Mini or iMac		
Control interface	SMEMA (conveyer)		
Data interface	USB and Thunderbolt		
Programming Interface	CSV Centroid file (Placement file)		
Repair/Monitor/SPC System/MES-interface	Mek Catch System (Windows 7/8/10) (option)		
3rd party Interfacing (MES) & Data Storage	Enterprise SQL DB/XML Files/Socket (Catch System Option)		
<i>General</i>			
Operating temperature	15-30 deg. C(60-90 deg. F)		
Operating humidity	15-80 % RH		
External size	W740 x D786 x H1236 (29.1" x 30.9" x 48.7")	W1040 x D1077 x H1270 (40.9" x 42.4" x 50.0")	W1190 x D1077 x H1259 (46.9" x 42.4" x 49.5")
Weight	180kg (397lbs)	240kg (529lbs)	290kg (639lbs)

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